

MIC-7700

Compact Fanless System with 6th/7th Gen Intel® Core™ i CPU Socket (LGA 1151)



Features

- Intel® 6th/7th Gen Core™ i CPU socket-type (LGA1151) with Intel® Q170/H110 chipset
- Wide operating temperature (-10 ~ 50 °C)
- VGA and DVI output
- 2 x GigaLAN and 8 x USB 3.0
- 1 x 2.5" HDD/SSD, 1 x CFast, and 1 x mSATA
- 2 x RS-232/422/485 and 4 x RS232 serial ports
- 9 ~ 36 V_{DC} input power range
- IP40 dust proof for deployment in harsh environment
- Supports FlexIO and iDoor technology, flexible configure additional HDMI, DVI, DIO, Remote switch IO
- Supports Advantech i-Modules
- Supports Advantech SUSI API and embedded software APIs
- Supports Intel® vPro™/AMT and TPM technologies
- Microsoft Azure Certified



Specifications

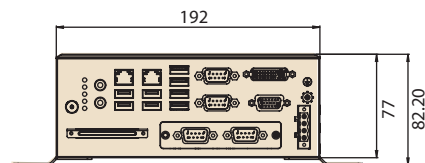
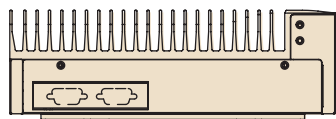
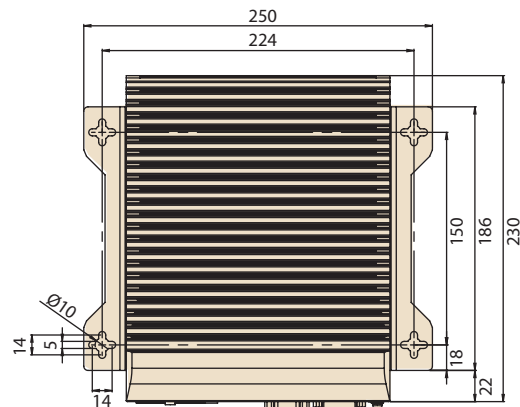
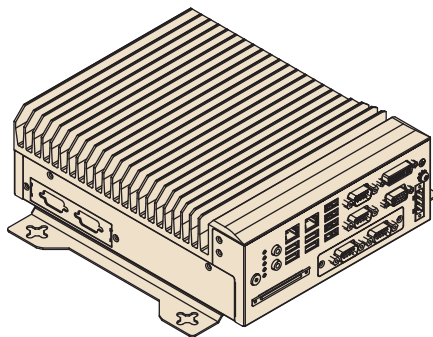
6 th /7 th Generation Processor* (TDP 35W)	CPU	i7-6700TE	i5-6500TE	i3-6100TE	G4400TE
	Core Number	4	4	2	2
	Base Frequency	2.4 GHz	2.3 GHz	2.7 GHz	2.9 GHz
	Max Turbo Frequency	3.4 GHz	3.3 GHz		
	L3 Cache	8 MB	6 MB	4 MB	3 MB
	Temperature	-10 ~ 50 °C (w/ industrial SSD, 0.7 m/s air flow)			
	Chipset	Q170/H110			
	BIOS	AMI 128Mb SPI Flash			
6 th /7 th Generation Processor* (TDP 65W)	CPU	i5-7500	i3-7101E	i5-6500	i3-6100
	Core Number	4	2	4	2
	Base Frequency	3.4 GHz	3.9 GHz	3.2 GHz	3.7 GHz
	Max Turbo Frequency	4.0GHz		3.6GHz	
	L3 Cache	6 MB	3 MB	6 MB	4 MB
	Temperature	-10 ~ 40 °C (w/ industrial SSD, 0.7 m/s air flow)			
	Chipset	Q170/H110			
	BIOS	AMI 128Mb SPI Flash			
Memory	Technology	Dual-channel DDR4 2133/2400 MHz (without ECC)			
	Socket	2 x 260-pin DDR4 SODIMM (up to 16 GB per socket)			
	Maximum Capacity	32GB			
Display	Chipset	7 th Gen. CPU: Intel HD Graphics 630, supports DirectX 12 6 th Gen. CPU: Intel HD Graphics 530/510, supports DirectX 12			
	VGA	1 x DB15, up to 2048 x 1152 maximum resolution			
	DVI	1 x DVI, up to 1920 x 1080 maximum resolution @ 30Mhz			
	Multiple Display	Q170: 3 x independent displays (with Flex I/O for 2nd DVI, 1 x HDMI or 1 x DP) H110: 2 x independent displays			
Ethernet	Controller	Q170 LAN1: Intel® I219LM, LAN2: Intel® i210IT H110 LAN1: Intel® I219V, LAN2: Intel® i210IT			
	Interface	2 x RJ45			
Storage	HDD	1 x 2.5" HDD/SSD (up to 2 x 2.5" SSD by optional kit; 2 x 3.5" HDD by i-Module)			
	CFast	1			
	mSATA	1			
	RAID	0/1/5/10 (MIC-7700Q only)			
	SATA Conn.	Q170: 3 x SATA signal, 3 x SATA power H110: 1 x SATA signal, 1x SATA power			
I/O	USB	Q170: 8 x USB 3.0 and 1 x internal USB 2.0 H110: 4 x USB 3.0 and 4 x USB 2.0			
	Serial Port	2 x DB9, 2 x RS-232/422/485 support auto flow control; 4 x RS-232 (with expansion cable)			
	Audio	2 (1 x line out and 1 x mic in)			
Expansion	Module	Supports Advantech i-Modules			
	Mini PCIe	Q170: 1 x mini PCIe (via USIM), 1 x mini PCIe/mSATA H110: 1 x mini PCIe (via USIM), 1 x mSATA			
LED and Switch	LED	2 (1 x Storage and 1 x Power), 4 for COM1 TX/RX and COM2 TX/RX			
	Button	1 x Power on/off switch			
Power	Type	ATX/AT			
	Input Voltage	9 ~ 36 V _{DC}			
	Power consumption	32.1W 116W			

Specifications (Cont.)

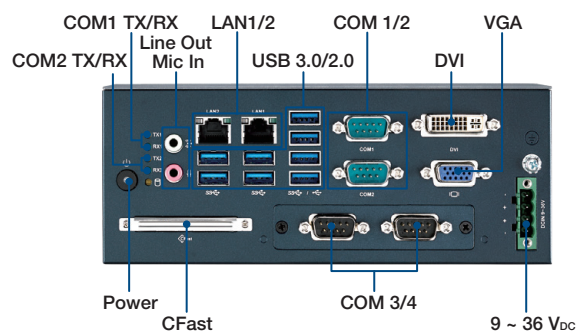
Watchdog Timer	Output Interval	System reset Programmable 1 ~ 255 sec/min		
Environment	Temperature	65W CPU w/ industrial wide-temp SSD -10 ~ 40 °C with 0.7 m/s air flow	35W CPU w/ industrial wide-temp SSD -10 ~ 50 °C with 0.7 m/s air flow	Non-operating -40 ~ 85 °C
	Humidity	95% @ 40 °C (non-condensing)		
	Vibration	With SSD: 3 Grms @ 5 ~ 500 Hz, random, 1 hr/axis With 2.5" HDD: 1 Grms @ 5 ~ 500 Hz, random, 1 hr/axis		2G
	Shock	With SSD: 20G, IEC-68-2-27, half-sine wave, 11 ms duration		50G 11 ms
Mechanical	Dimensions (W x H x D)	77 x 192 x 230 mm (3.07" x 7.55" x 9.05")		
	Weight	2.8 kg (6.17 lbs)		
	Installation	Desktop/wall mount		
Certifications	EMC	CE/FCC Class A, CCC, BSMI		
	Safety	UL, CCC, BSMI		
OS Support		7th Gen. CPU: Windows 10, Windows 10 IoT 6th Gen. CPU: Windows 10, Windows 10 IoT, Windows 8.1 (64 bit), Windows 7 Linux OS		

Dimensions

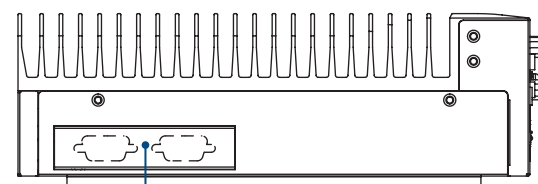
Unit: mm



Front View



Side View



iDoor or 2 x RS-232 expansion slots